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United States Patent [19]

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Siegel et al.

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[54] **LOW-PROFILE DETACHABLE INTEGRATED CIRCUIT MODULE**

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[73] Assignee: **SGS-Thomson Microelectronics, Inc., Carrollton, Tex.**

[**] Term: **14 Years**

[21] Appl. No.: **21,052**

[22] Filed: **Apr. 8, 1994**

[52] U.S. Cl. **D13/182**

[58] Field of Search **D13/182; 361/728, 747, 361/807, 809, 820, 783; 174/52.1, 52.4, 260; 257/723**

[56] **References Cited**

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[57] **CLAIM**

The ornamental design for the low-profile detachable integrated circuit module, as shown and described.

DESCRIPTION

FIG. 1 is a perspective view of the low-profile detachable integrated circuit module illustrating its cooperative relationship with a packaged integrated circuit. The broken line showing of the packaged integrated circuit is included for the purpose of illustrating an environmental element only and forms no part of the claimed design;

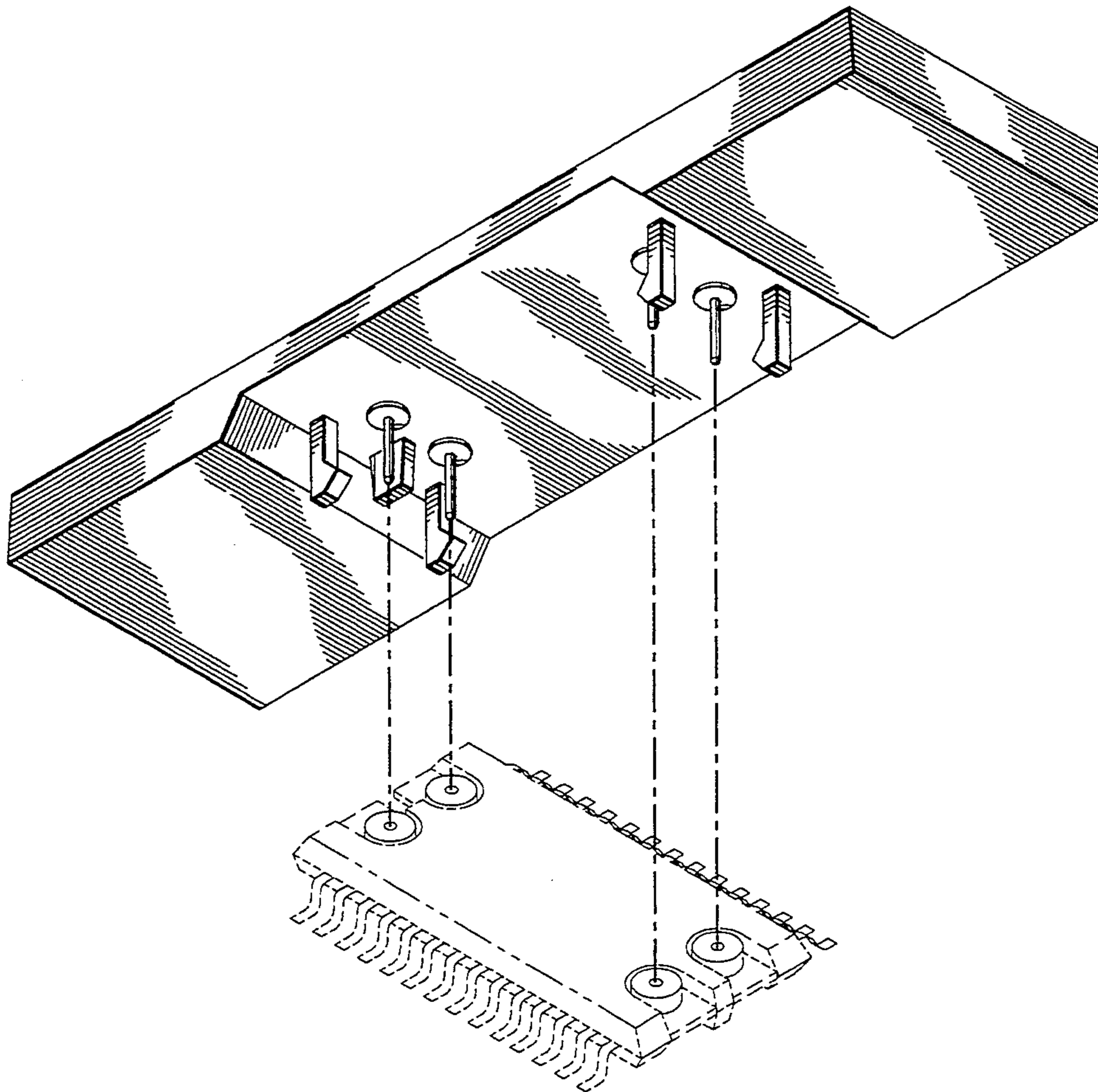
FIGS. 2 and 3 are opposing side elevation views of the detachable module;

FIG. 4 is an end elevation view of the detachable module from its end nearer the lockout key;

FIG. 5 is an end elevation view of the detachable module from its end opposite that from the lockout key;

FIG. 6 is a top plan view of the detachable module; and,

FIG. 7 is a bottom plan view of the detachable module.



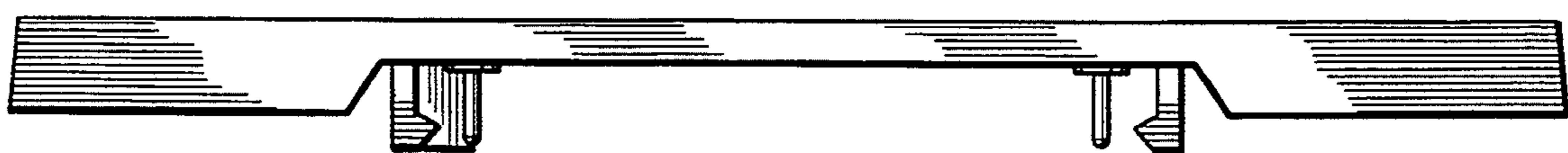
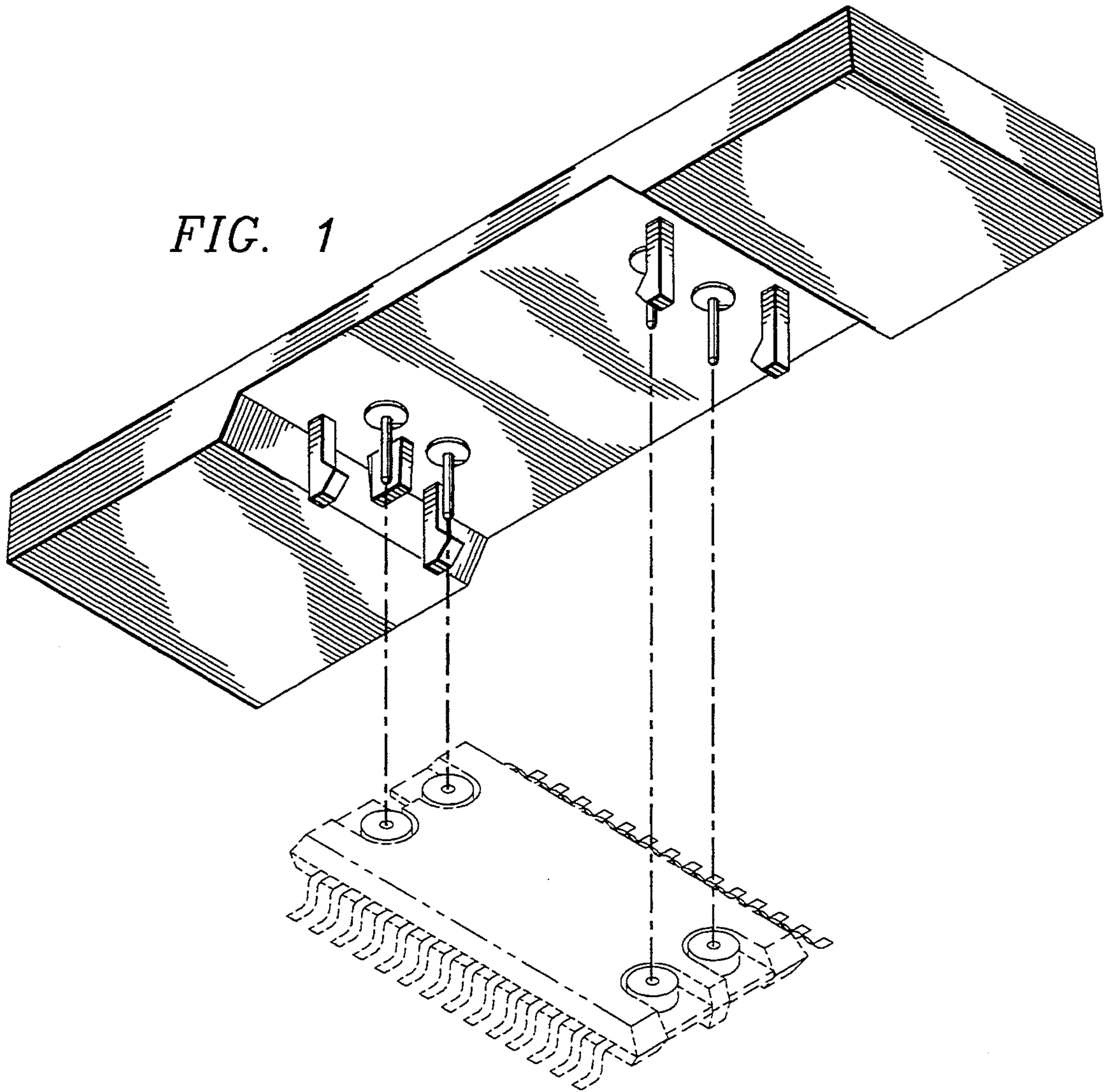


FIG. 2

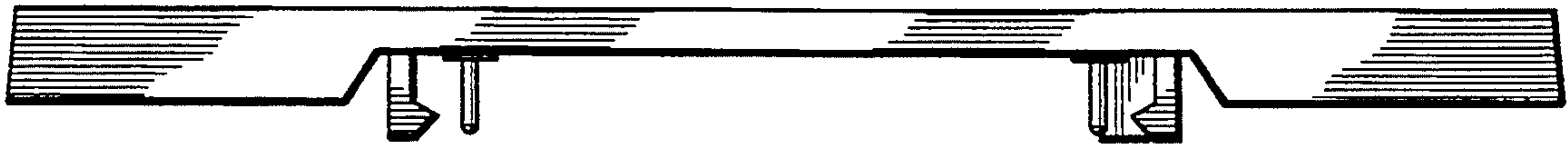


FIG. 3

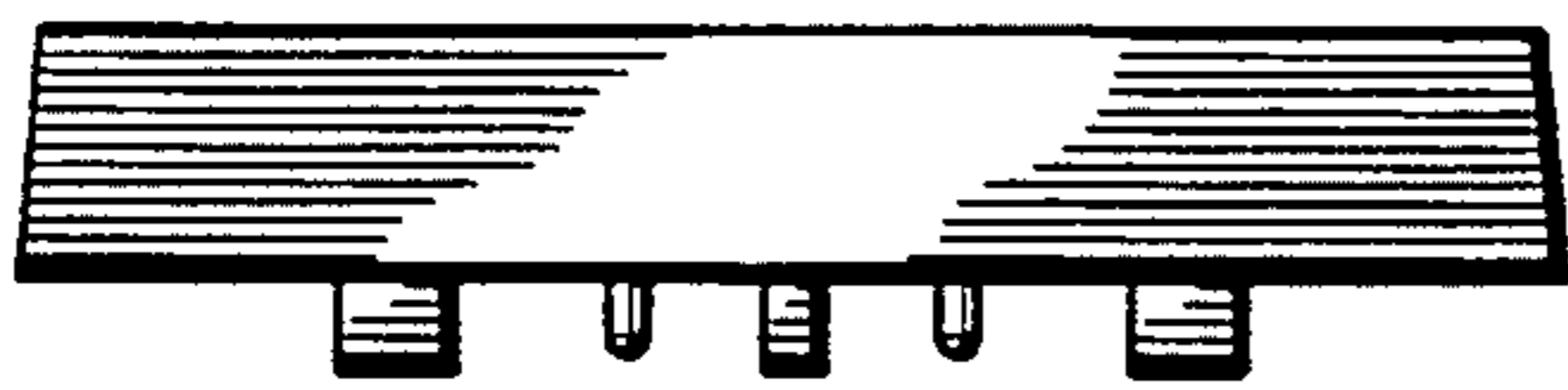


FIG. 4

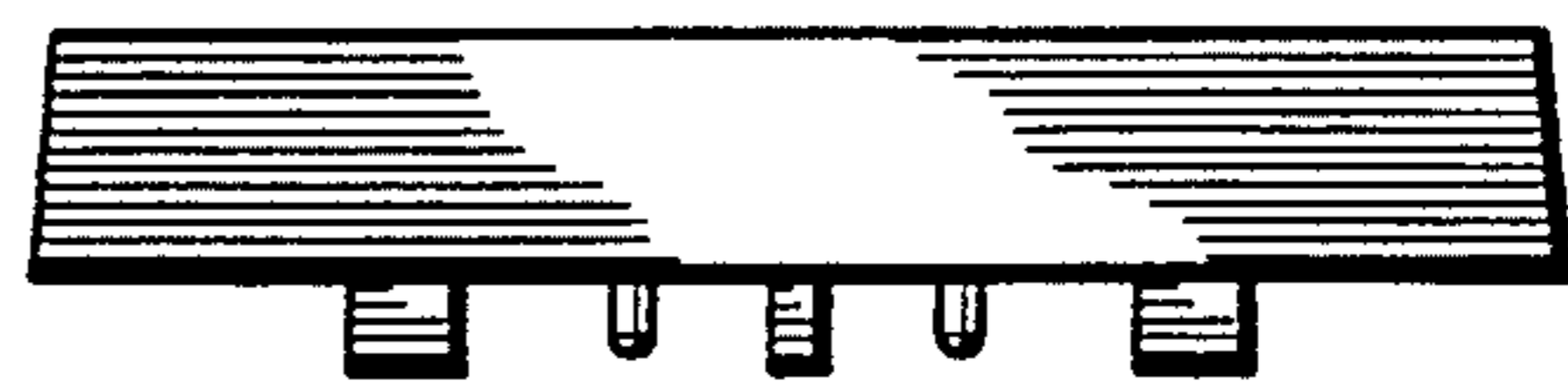


FIG. 5

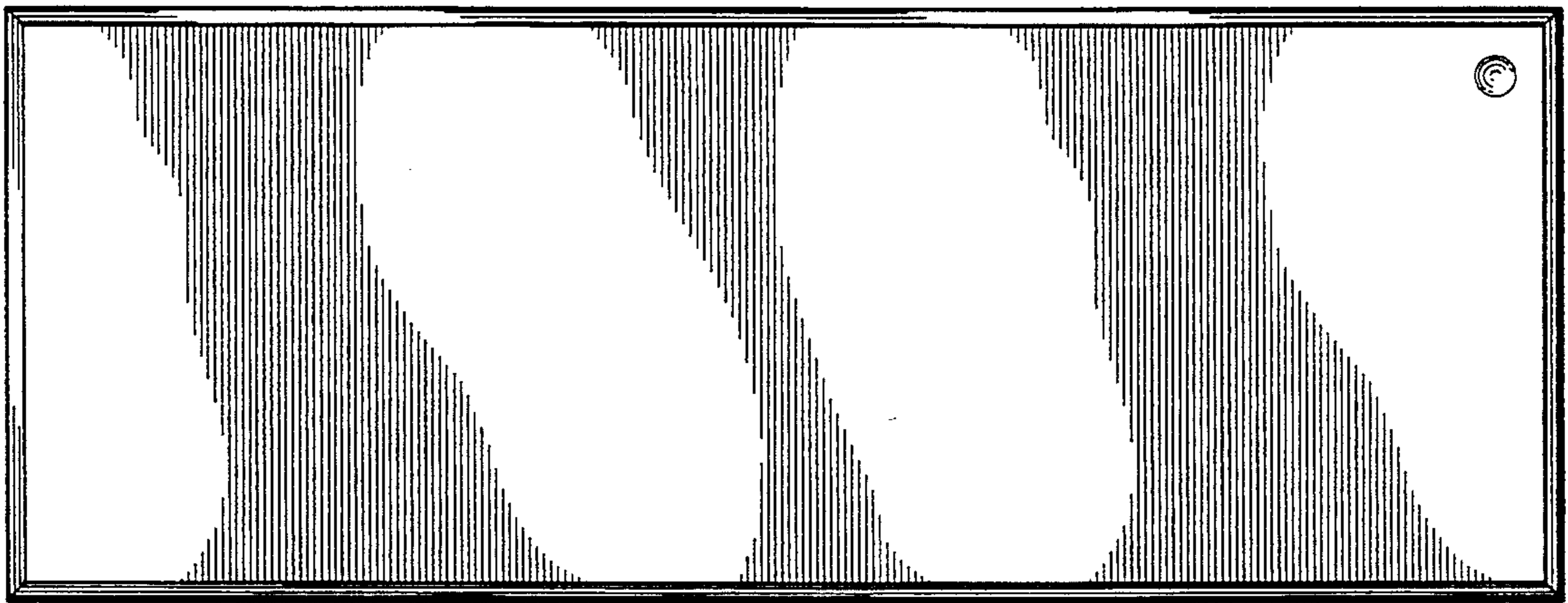


FIG. 6

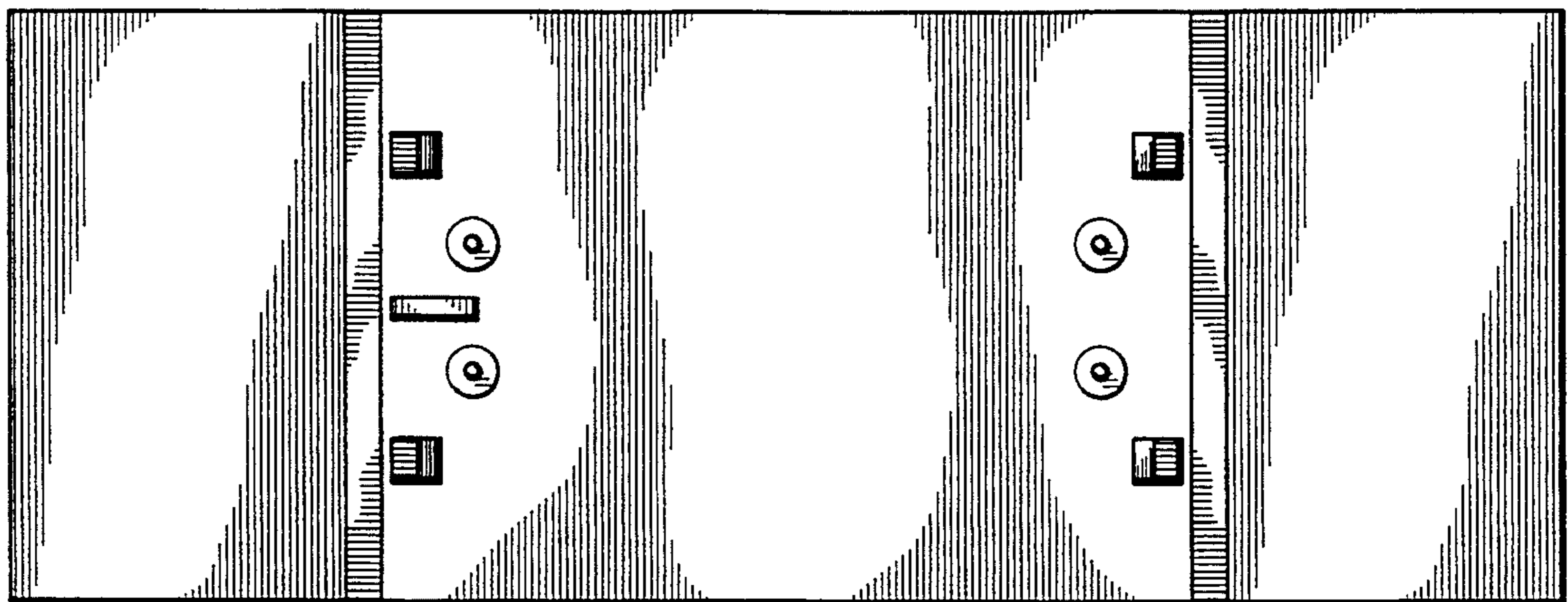


FIG. 7